



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2811
Primary Examiner: Mr. Ori Nadav

In Re PATENT APPLICATION OF

Applicants: Shih-Hsien WU et al.
Appln. No.: 10/619,591
Conf. No.: 7448
Filed: July 16, 2003
For : COMPOSITE LAMINATED
SUBSTRATE COMPOSED OF
LAMINATED INORGANIC AND
ORGANIC SUBSTRATES
(As amended)
Atty. Dkt.: TAIW 813

**REQUEST FOR
APPROVAL OF
DRAWING CHANGES**

MAIL STOP RCE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This Request For Approval of Drawing Changes accompanies a Request For Continued Examination and an Amendment.

Attached are Figs. 3 and 5 as originally filed with proposed changes shown in red ink. These figures show an inorganic substrate 20 including a plurality of printed circuit boards 21. Thus, as in Figures 1, 2, 4, and 7, each printed circuit board 21 of the plurality should have been numbered "21", but inadvertently this was not done.

Support for these changes is submitted to be found in the Application as filed as follows.

"[0031] FIG. 3 shows a sectional view of a third embodiment of the invention. The construction different from that of the first embodiment is that the inorganic substrate 10 is made of a ceramic substrate." Thus, Applicants submit that Fig. 3 should have shown each printed circuit board 21 of the plurality with the numeral "21" as in Fig. 1 which relates to the first embodiment in which, "[0028] The organic substrate 20 covers the side of the inorganic substrate 10. Each organic substrate 20 is composed of a plurality of printed circuit boards 21."

"[0034] FIG. 5 shows a sectional view of a fifth embodiment of the invention. The construction different from that of the fourth embodiment is that the inorganic substrate 10 is covered by a covering layer 40 and bonded with two organic substrates 20 fixed outside, so that the inorganic substrate 10 is fully covered [sic by] the organic substrates 20." Thus, Applicants submit that Fig. 5 should have shown each printed circuit board 21 of the plurality with the numeral "21" as in Fig. 4 which relates to the fourth embodiment in which, "[0033] FIG. 4 shows a sectional view of a fourth embodiment of the invention. The construction different from that of the first embodiment is that the outer printed circuit board 21 is formed with a build-up substrate 22 through build-up process. "


Applicants are desirous of placing this Application in the best condition for allowance and have just now noticed the foregoing. Accordingly, the Examiner is respectfully requested to review and approve of these proposed drawing changes because they correct inadvertent errors and, thus, advance prosecution.

In anticipation of the Examiner's approval, additionally attached are replacement

sheets of Figs. 3 and 5 which include these changes.

Respectfully submitted,

Due: September 4, 2007
Date


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